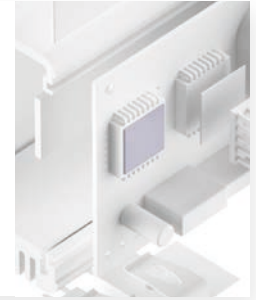


PHASE CHANGE COMPOUND TPC-W-PC-M/-E HALA

printable

TPC-W-PC is a thixotropic thermally conductive phase changing compound optimising the thermal path e.g. between electronic packages and heat sinks. During warm-up the phase change compound starts filling up surface-specific roughnesses and unevennesses and expels any air enclosures from micro structures even at very low pressure. Both thin bondline and high thermal conductivity minimise the total thermal resistance. It can be pre-applied by screen printing. After drying the compound is dry-to-the-touch and ready for use on the thermal contact area. TPC-W-PC-M and TPC-W-PC-E are printable compounds with alternatively long and extended dry times. TPC-W-PC-E dries only at elevated temperature.



Release 03 / 2020

PROPERTIES

- Optimal thermal contact by thin bondline
- Silicone-free
- Thermal conductivity: 3.5 W/mK
- Thixotropic
- Ideal alternative and replacement of messy thermal grease
- Accurate automated application by stencil printing for mass production
- TPC-W-PC-M med dry time: @ RT or elevated temp.
- TPC-W-PC-E extended dry time: only @ elevated temp.

AVAILABILITY

- TPC-W-PC-M and TPC-W-PC-E: Printable type med dry -M and extended dry -E
- E dries at elevated temperature only
- 360 ml SEMCO cartridges (transparent)
- 30 ml syringes

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs und IGBTs
- Memory Modules
- IGBT Power Modules
- CPUs

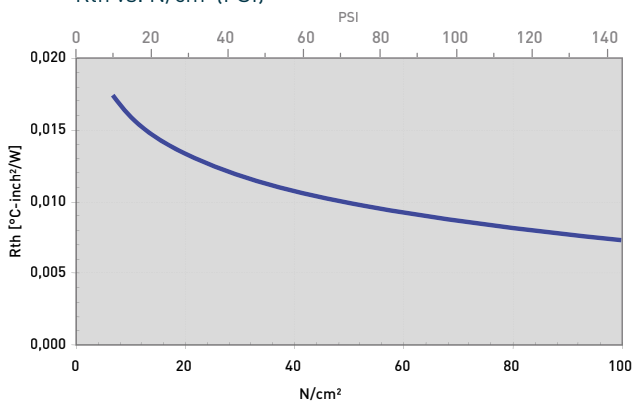
For use in Servo drive control units / Computers / Automation appliances / Microelectronics

Technical Data Sheet

PROPERTY	UNIT	TPC-W-PC-M	TPC-W-PC-E
MATERIAL			
		Dryable Phase Change Compound	Dryable Phase Change Compound
Colour		Grey	Grey
Assembly		~ Print	~ Print
Specific Gravity dried	g/cm³	1.8 @ RT	1.8 @ RT
undried	g/cm³	1.6 @ RT	1.7 @ RT
Viscosity dried @ 10 rpm	Pas	60 @ 60°C / 42 @ 80°C / 25 @ 100°C / 18 @ 120°C	60 @ 60°C / 42 @ 80°C / 25 @ 100°C / 18 @ 120°C
Viscosity undried @ 10 rpm	Pas	85 @ RT	96 @ RT
Drying @ Temperature	Time	@ 22°C: 24 h (0.05 mm) 48 h (0.15 mm) 56 h (0.25 mm)	@ 60°C: 3,5 h (0.05 mm) 8 h (0.15 mm) 13 h (0.25 mm)
@ Thickness		@ 60°C: 24 min (0.05 mm) 50 min (0.15 mm) 60 min (0.25 mm)	@ 125°C: 8 min (0.05 mm) 15 min (0.15 mm) 20 min (0.25 mm)
Storage (@ RT)	Months	9	9
RoHS Conformity	2015/863/EU	Yes	Yes
THERMAL			
Resistance¹ @ 150 PSI	°C-inch²/W	0.007	0.007
Resistance¹ @ 30 PSI	°C-inch²/W	0.013	0.013
Resistance¹ @ 10 PSI	°C-inch²/W	0.017	0.017
Thermal Conductivity	W/mK	3.5	3.5
Phase Change Temperature	°C	ca. 45	ca. 45
Operating Temperature Range	°C	< 110	< 110
Max. Storage Temp.	°C	25	25

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Rth vs. N/cm² (PSI)



All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.